



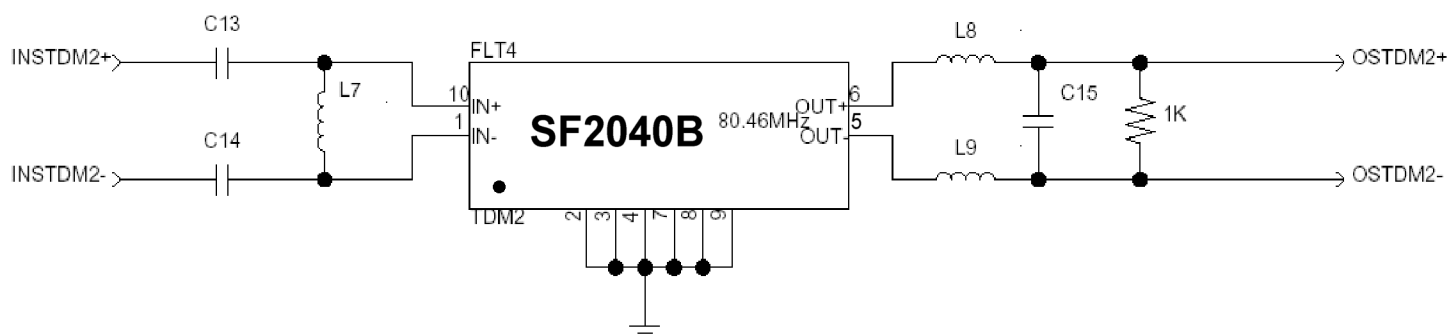
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

Matching Circuit and Matching Component Values Used in G3 Sirius Radios

(Refer to Sirius Radio G3 Chipset Application Note, Doc. #RX000104-B, Sec. 4.2.5)

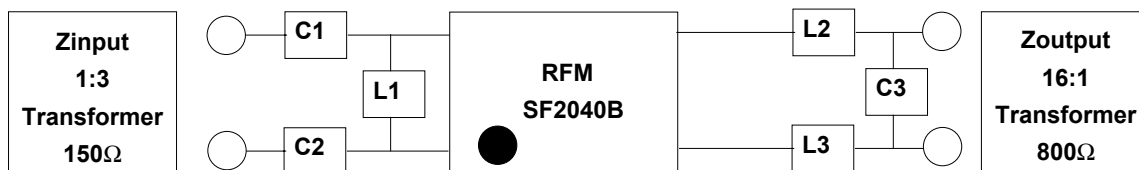


TDM2 Narrowband SAW Matching Circuit

TDM2 Narrowband SAW Matching Values

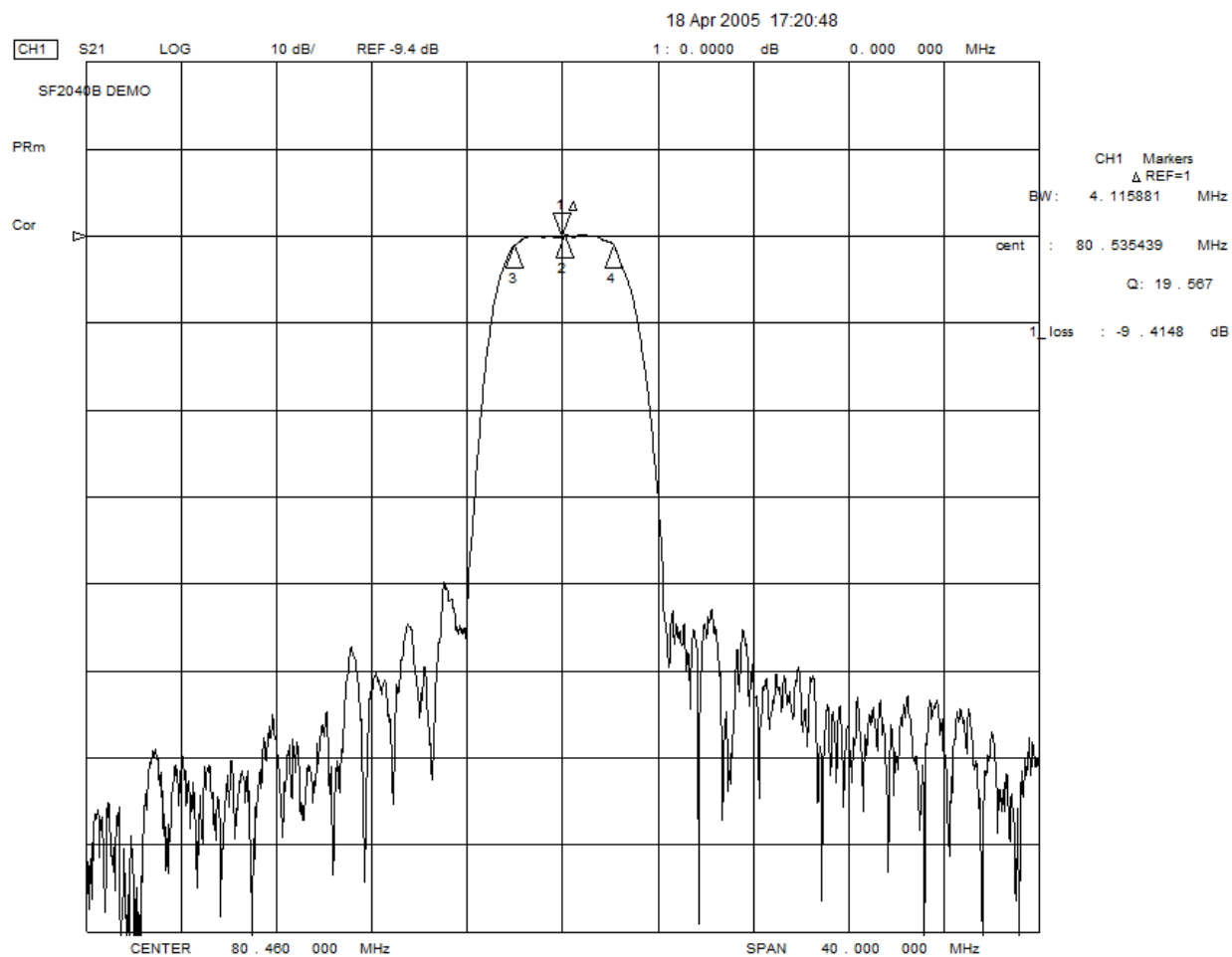
Reference Designator	Value
C13	12 pF
C14	12 pF
L7	240 nH
L8	390 nH
L9	390 pF
C15	10 pF

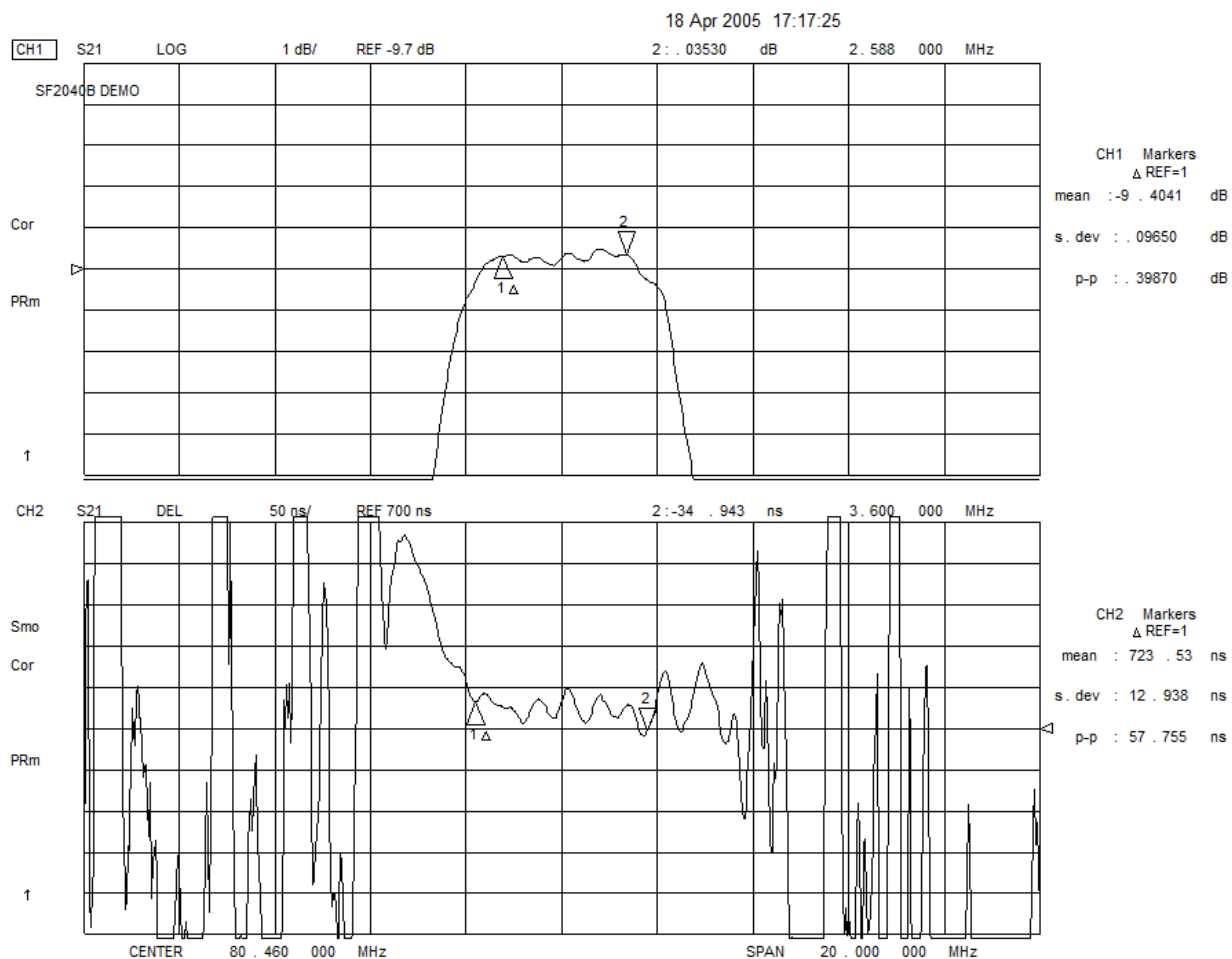
Matching Circuit and Matching Component Values Used on Filter Demo Board



SF2040B
80.460 MHz

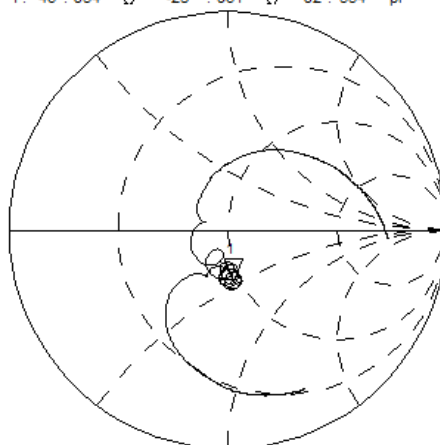
C1 = 9pF
C2 = 9pF
L1 = 270nH
L2 = 330nH
L3 = 330pF
C3 = 12pF





18 Apr 2005 17:09:52
 CH1 S11 1 UFS 1: 46.854 Ω -23.961 Ω 82.554 pF 80.460 000 MHz
 SF2040B DEMO

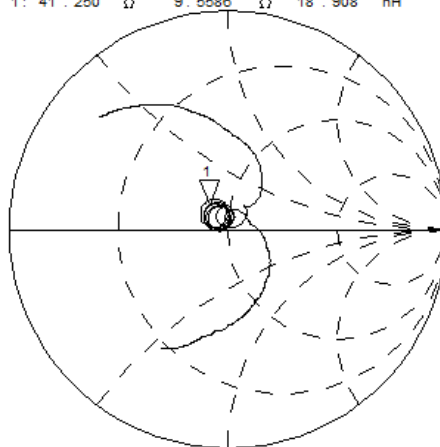
PRm



↑

CH2 S22 1 UFS 1: 41.250 Ω 9.5586 Ω 18.908 nH 80.460 000 MHz

PRm



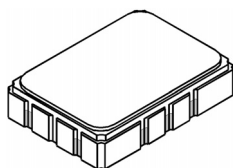
↑

CENTER 80.460 000 MHz SPAN 20.000 000 MHz

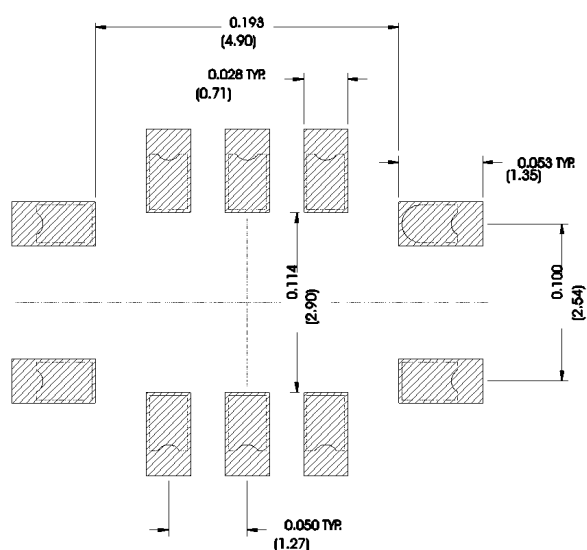
SMP-03 Case

10-Terminal Ceramic Surface-Mount Case

7 x 5 mm Nominal Footprint



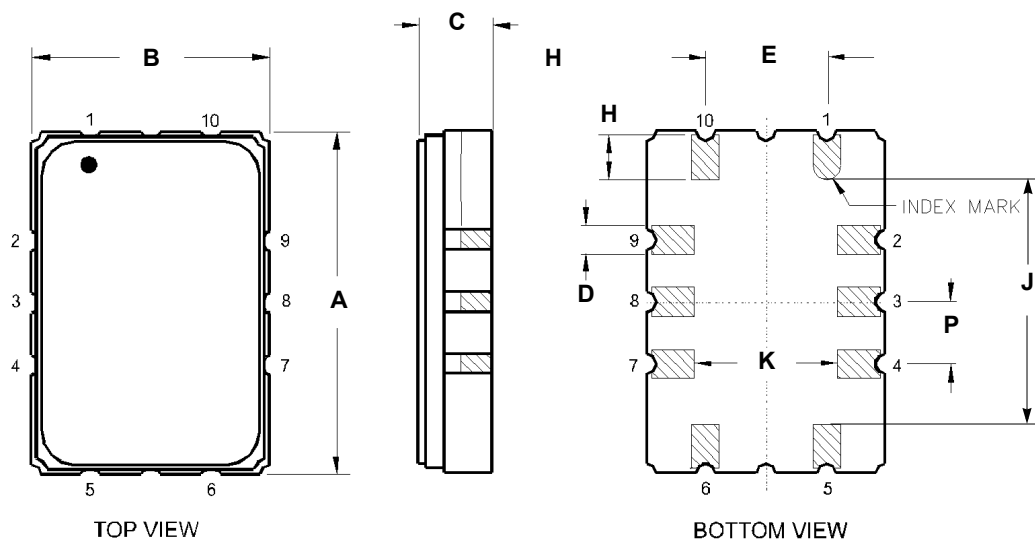
Recommended PCB Footprint



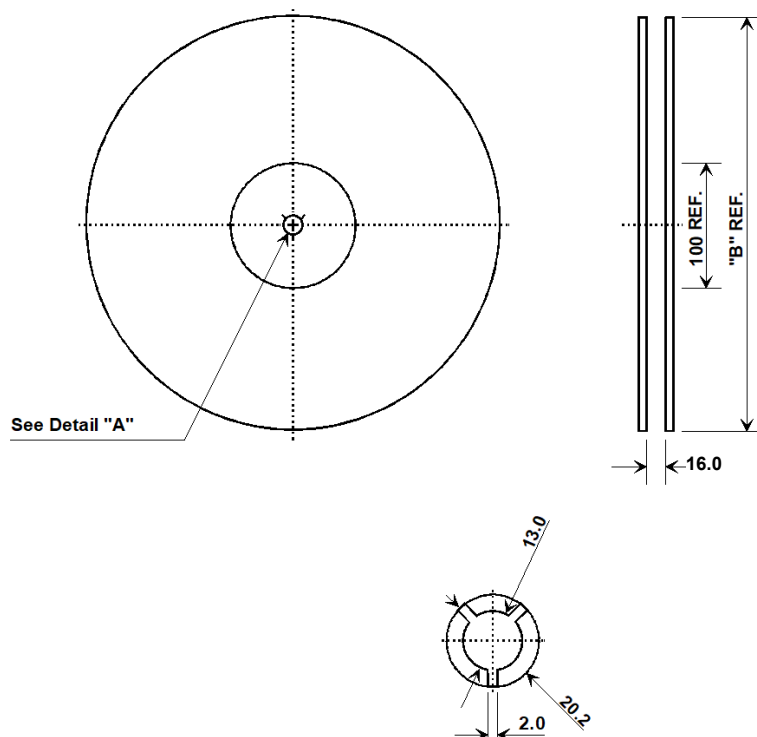
Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot



Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

Product Reflow/ESD/MSL

Reflow Peak Temperature	265	°C
Reflow Peak Time	10	Seconds
Liquidus 217 Temperature/Time	110	Seconds
Over Liquidus 230 Temperature/Time	70	Seconds
Reflow Condition	SMT	
Class Level HBM	2	
HBM(V)	2000	HBM(V)
MM(V)	N/A	MM(V)
CDM(V)	2000	CDM(V)
MSL	1	

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

